

SOT632A

leadless surface mounted package; plastic cap; 12 terminations

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QMAN12
Package type industry code	QMAN12
Package style descriptive code	QMAN (quad microelectronic assembly; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.45	-	13.75	14.05	mm
E	package width		7.7	-	8	8.3	mm
A	seated height		1.4	-	1.6	1.8	mm
n ₂	actual quantity of termination		-	-	12	-	



2. Package outline

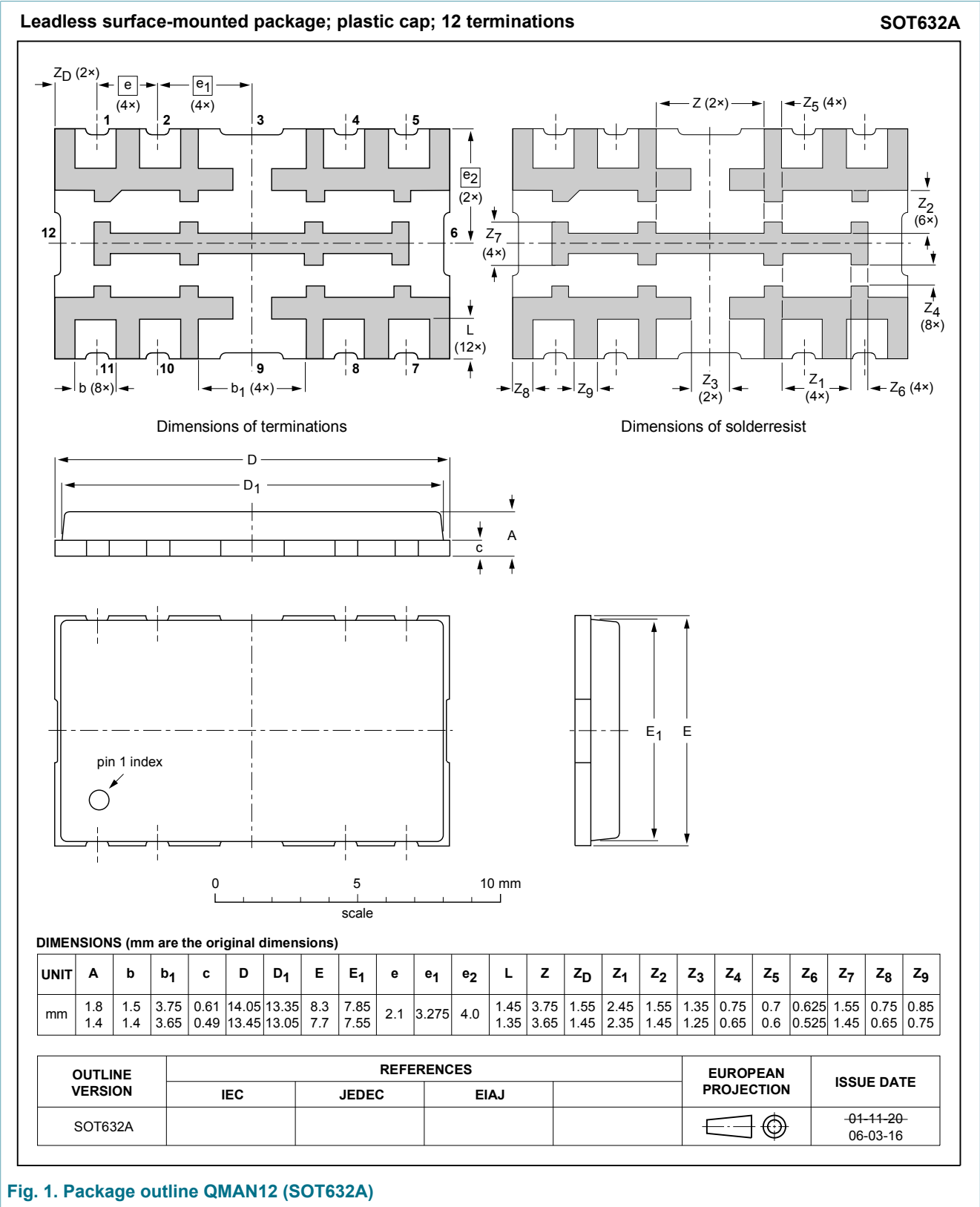


Fig. 1. Package outline QMAN12 (SOT632A)

3. Legal information

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